

LNPTM LUBRICOMPTM COMPOUND 0X88533

PDX-O-88533

DESCRIPTION

LNP LUBRICOMP OX88533 compound is based on Polyphenylene Sulfide (PPS) resin containing 30% glass fiber and 15% PTFE. Added features of this grade include: Wear Resistant.

GENERAL INFORMATION	
Features	Wear resistant
Fillers	Glass Fiber, PTFE
Polymer Types	Polyphenylene Sulfide, Linear (PPS, Linear)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Building Component
Consumer	Sport/Leisure, Personal Accessory, Home Appliances, Commercial Appliance
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, break	144	MPa	ASTM D638
Tensile Strain, break	1.8	%	ASTM D638
Tensile Modulus, 50 mm/min	13100	MPa	ASTM D638
Flexural Stress	200	MPa	ASTM D790
Flexural Modulus	10960	MPa	ASTM D790
Tensile Stress, break	146	MPa	ISO 527
Tensile Strain, break	1.8	%	ISO 527
Tensile Modulus, 1 mm/min	12180	MPa	ISO 527
Flexural Stress	208	MPa	ISO 178
Flexural Modulus	11440	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	528	J/m	ASTM D4812
Izod Impact, notched, 23°C	85	J/m	ASTM D256
Instrumented Dart Impact Energy @ peak, 23°C	7	J	ASTM D3763
Multiaxial Impact	3	J	ISO 6603
Izod Impact, unnotched 80*10*4 +23°C	38	kJ / m²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	9	kJ/m²	ISO 180/1A
THERMAL ⁽¹⁾			
HDT, 1.82 MPa, 3.2mm, unannealed	263	°C	ASTM D648
HDT/Af, 1.8 MPa Flatw 80°10°4 sp=64mm	260	°C	ISO 75/Af

© 2024 Copyright by SABIC. All rights reserved

CHEMISTRY THAT MATTERS

Revision 20231109



PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
PHYSICAL ⁽¹⁾			
Density	1.69	g/cm ³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.01	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.1	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.5	%	ASTM D955
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.09	%	ISO 294
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.53	%	ISO 294
Wear Factor Washer	59	10^-10 in^5-min/ft-lb-hr	ASTM D3702 Modified: Manual
Dynamic COF	0.43	-	ASTM D3702 Modified: Manual
Static COF	0.34	-	ASTM D3702 Modified: Manual
Density	1.69	g/cm ³	ISO 1183
INJECTION MOLDING (3)			
Drying Temperature	120 - 150	°C	
Drying Time	4	Hrs	
Melt Temperature	315 – 320	°C	
Front - Zone 3 Temperature	330 - 345	°C	
Middle - Zone 2 Temperature	320 - 330	°C	
Rear - Zone 1 Temperature	305 – 315	°C	
Mold Temperature	140 – 165	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 - 60	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

DISCLAIMER

Any sale by SABIC, its subsidiaries and affiliates (each a "seller"), is made exclusively under seller's standard conditions of sale (available upon request) unless agreed otherwise in writing and signed on behalf of the seller. While the information contained herein is given in good faith, SELLER MAKES NO WARRANTY, EXPRESS OR IMPLIED, INCLUDING MERCHANTABILITY AND NONINFRINGEMENT OF INTELLECTUAL PROPERTY, NOR ASSUMES ANY LIABILITY, DIRECT OR INDIRECT, WITH RESPECT TO THE PERFORMANCE, SUITABILITY OR FITNESS FOR INTENDED USE OR PURPOSE OF THESE PRODUCTS IN ANY APPLICATION. Each customer must determine the suitability of seller materials for the customer's particular use through appropriate testing and analysis. No statement by seller concerning a possible use of any product, service or design is intended, or should be construed, to grant any license under any patent or other intellectual property right.